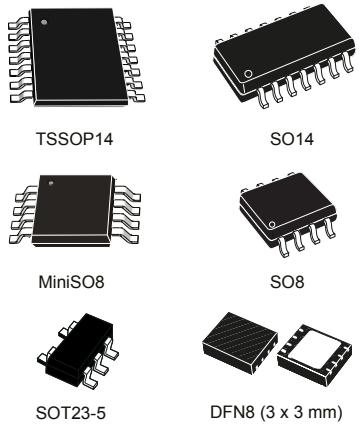


### Low power, 1.7 MHz, rail-to-rail output, 36 V operational amplifier



#### Features

- Low offset voltage: 1 mV max. @ 25 °C
- Low current consumption: 375 µA max. / operator @ 36 V
- Wide supply voltage: 2.7 to 36 V
- Gain bandwidth product: 1.7 MHz
- Unity gain stable
- Rail-to-rail output
- Input common mode voltage includes ground
- High ESD tolerance: 4 kV HBM
- EMI hardened
- Extended temperature range: -40 to 125 °C
- Automotive qualification

#### Applications

- Industrial
- Power supplies
- Automotive

#### Maturity status link

[TSB621, TSB622, TSB624](#)

#### Related products

TSB611, TSB612	For lower power consumption
TSB571, TSB572, TSB514	For higher speed and rail- to-rail inputs
TSB711, TSB712	For a higher precision and speed

#### Description

The **TSB621, TSB622, TSB624** are general purpose operational amplifiers featuring an extended supply voltage operating range and rail-to-rail output. They also offer an excellent speed/power consumption ratio with 1.7 MHz gain bandwidth product while consuming less than 375 µA per operator at 36 V supply voltage.

The **TSB621, TSB622, TSB624** operate over a wide temperature range from -40 °C to 125 °C making these devices ideal for industrial and automotive applications with the associated qualification.

Thanks to the small package size, the **TSB621, TSB622, TSB624** can be used in applications where space on the board is limited. It can thus reduce the overall cost of the PCB.

## 1 Pin connections

Figure 1. TSB621 pin connections (top view)

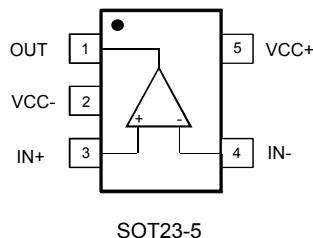
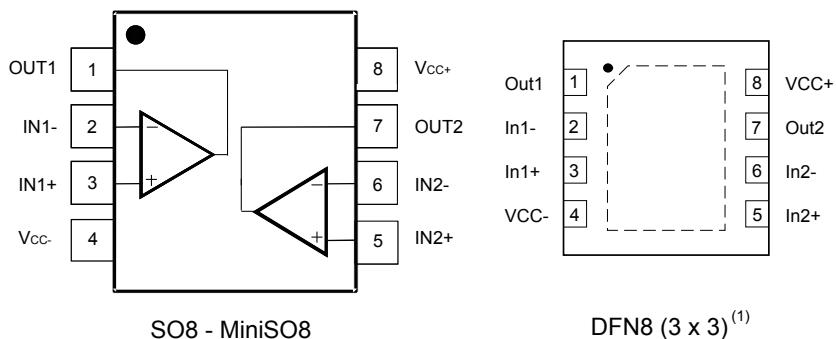


Table 1. TSB621 pin description

Pin n°	Pin name	Description
1	OUT1	Output
2	VCC -	Negative supply voltage
3	IN +	Positive input voltage
4	IN -	Negative input voltage
5	VCC	Positive supply voltage

Figure 2. TSB622 pin connections (top view)

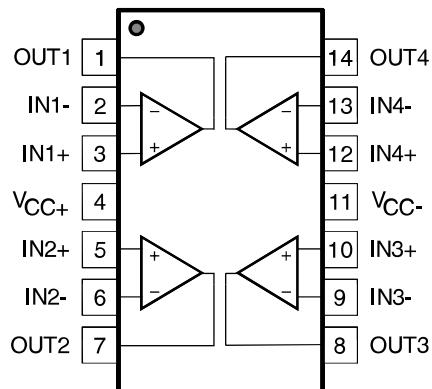


(1) Exposed pad can be left floating or connected to ground.

Table 2. TSB622 pin description

Pin n°	Pin name	Description
1	OUT1	Output
2	IN1 -	Negative input voltage
3	IN1 +	Positive input voltage
4	VCC -	Negative supply voltage
5	IN2 +	Positive input voltage
6	IN2 -	Negative input voltage
7	OUT2	Output
8	VCC +	Positive supply voltage

Figure 3. TSB624 pin connections (top view)



SO14 - TSSOP14

Table 3. TSB624 pin description

Pin n°	Pin name	Description
1	OUT1	Output
2	IN1 -	Negative input voltage
3	IN1 +	Positive input voltage
4	VCC +	Positive supply voltage
5	IN2 +	Positive input voltage
6	IN2 -	Negative input voltage
7	OUT2	Output
8	OUT3	Output
9	IN3 -	Negative input voltage
10	IN3 +	Positive input voltage
11	VCC -	Negative supply voltage
12	IN4 +	Positive input voltage
13	IN4 -	Negative input voltage
14	OUT4	Output

## 2 Absolute maximum ratings and operating conditions

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{cc}$	Supply voltage <sup>(1)</sup>	40	V
$V_{id}$	Differential input voltage <sup>(2)</sup>	$\pm V_{cc}$	V
$V_{in}$	Input voltage	$(V_{cc-}) -0.2$ to $(V_{cc+}) +0.2$	V
$I_{in}$	Input current <sup>(3)</sup>	10	mA
$T_{stg}$	Storage temperature	-65 to 150	°C
$T_j$	Junction temperature	150	°C
$R_{th-jA}$	Thermal resistance junction to ambient <sup>(4) (5)</sup>		
	SO8	125	
	MiniSO8	190	
	DFN8 3x3 WF	40	°C/W
	SOT23-5	250	
	SO14	105	
ESD	TSSOP14	100	
	Human Body Model (HBM TSB621, TSB622) <sup>(6)</sup>	4000	
	Human Body Model (HBM TSB624) <sup>(6)</sup>	3000	V
	Charged Device Model (CDM) <sup>(7)</sup>	1500	

1. All voltage values, except differential voltage, are with respect to network ground terminal.
2. The differential voltage is the non-inverting input terminal with respect to the inverting input terminal.
3. Input current must be limited by a resistor in series with the inputs.
4.  $R_{th}$  are typical values.
5. Short-circuits can cause excessive heating and destructive dissipation.
6. According to JEDEC standard JESD22-A114F.
7. According to ANSI/ESD STM5.3.1.

Table 5. Operating conditions

Symbol	Parameter	Value	Unit
$V_{cc}$	Supply voltage	2.7 to 36	V
$V_{icm}$	Common mode voltage on input pins	$(V_{cc-}) -0.1$ to $(V_{cc+}) -1$	V
T	Operating free-air temperature range	-40 to 125	°C

### 3 Electrical characteristics

**Table 6. Electrical characteristics  $V_{CC+} = 2.7 \text{ V}$ ,  $V_{CC-} = 0 \text{ V}$ ,  $V_{icm} = V_{CC}/2$ ,  $T = 25^\circ\text{C}$ ,  $R_L = 10 \text{ k}\Omega$  connected to  $V_{CC}/2$  (unless otherwise specified)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>DC performance</b>						
$V_{IO}$	Input offset voltage	$T = 25^\circ\text{C}$	-1		1	mV
		$T_{min} < T < T_{max}$	-1.6		1.6	
$ \Delta V_{IO}/\Delta T $	Input offset voltage drift	$T_{min} < T < T_{max}$		2		$\mu\text{V}/^\circ\text{C}$
$I_{IB}$	Input bias current	$T = 25^\circ\text{C}$		15	30	nA
		$T_{min} < T < T_{max}$			45	
$I_{IO}$	Input offset current	$T = 25^\circ\text{C}$		3	10	
		$T_{min} < T < T_{max}$			15	
CMR	Common mode rejection ratio: $20 \log (\Delta V_{icm}/\Delta V_{io})$	$V_{icm} = -0.1 \text{ to } V_{CC} - 1 \text{ V}$	90	115		dB
		$V_{OUT} = V_{CC}/2$				
		$T_{min} < T < T_{max}$	85			
$A_{VD}$	Large signal voltage gain	$V_{OUT} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	90	105		dB
		$T_{min} < T < T_{max}$	82			
$V_{OH}$	High-level output voltage, $V_{OH} = V_{CC} - V_{OUT}$	$T = 25^\circ\text{C}$		35	46	mV
		$T_{min} < T < T_{max}$			55	
$V_{OL}$	Low-level output voltage	$T = 25^\circ\text{C}$		50	60	mV
		$T_{min} < T < T_{max}$			75	
$I_{OUT}$	$I_{sink}$	$V_{OUT} = V_{CC}$	20	27		mA
		$T_{min} < T < T_{max}$	10			
	$I_{source}$	$V_{OUT} = 0 \text{ V}$	20	28		
		$T_{min} < T < T_{max}$	8			
$I_{CC}$	Supply current (per channel)	No load, $V_{OUT} = V_{CC}/2$		280	330	$\mu\text{A}$
		$T_{min} < T < T_{max}$			400	
<b>AC performance</b>						
GBP	Gain bandwidth product	$R_L = 10 \text{ k}\Omega$ , $C_L = 100 \text{ pF}$	1	1.45		MHz
		$T_{min} < T < T_{max}$	0.7			
$\Phi_m$	Phase margin	$R_L = 10 \text{ k}\Omega$ , $C_L = 100 \text{ pF}$		45		degrees
$G_m$	Gain margin			18		dB
SR	Slew rate	$T = 25^\circ\text{C}$	0.30	0.53		$\text{V}/\mu\text{s}$
		$T_{min} < T < T_{max}$	0.20			
$E_N$	Equivalent input noise voltage	$f = 1 \text{ kHz}$		30		$\text{nV}/\sqrt{\text{Hz}}$
THD+N	Total harmonic distortion + noise	$f_{in} = 1 \text{ kHz}$ , Gain = 1, $R_L = 100 \text{ k}\Omega$ , $V_{icm} = (V_{CC} - 1 \text{ V}) / 2$ , BW = 22 kHz, $V_{OUT} = 1 \text{ Vpp}$		0.005		%
$C_S$	Channel separation	$f = 1 \text{ kHz}$		120		dB
$t_{rec}$	Overload recovery time			2		$\mu\text{s}$

**Table 7. Electrical characteristics  $V_{CC+} = 12 \text{ V}$ ,  $V_{CC-} = 0 \text{ V}$ ,  $V_{icm} = V_{CC}/2$ ,  $T = 25^\circ\text{C}$ ,  $R_L = 10 \text{ k}\Omega$  connected to  $V_{CC}/2$  (unless otherwise specified)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>DC performance</b>						
$V_{IO}$	Input offset voltage	$T = 25^\circ\text{C}$	-1		1	mV
		$T_{min} < T < T_{max}$	-1.6		1.6	
$ \Delta V_{IO}/\Delta T $	Input offset voltage drift	$T_{min} < T < T_{max}$		2		$\mu\text{V}/^\circ\text{C}$
$I_{IB}$	Input bias current	$T = 25^\circ\text{C}$		15	30	nA
		$T_{min} < T < T_{max}$			45	
$I_{IO}$	Input offset current	$T = 25^\circ\text{C}$		3	10	nA
		$T_{min} < T < T_{max}$			15	
CMR	Common mode rejection ratio: $20 \log (\Delta V_{icm}/\Delta V_{io})$	$V_{icm} = -0.1 \text{ to } V_{CC} - 1 \text{ V}$ , $V_{OUT} = V_{CC}/2$	100	130		dB
		$T_{min} < T < T_{max}$	95			
		$V_{OUT} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	98	115		
AvD	Large signal voltage gain	$T_{min} < T < T_{max}$	90			dB
		$V_{OUT} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	98	115		
$V_{OH}$	High-level output voltage, $V_{OH} = V_{CC} - V_{OUT}$	$T = 25^\circ\text{C}$		68	80	mV
		$T_{min} < T < T_{max}$			95	
$V_{OL}$	Low-level output voltage	$T = 25^\circ\text{C}$		86	100	mV
		$T_{min} < T < T_{max}$			125	
$I_{OUT}$	$I_{sink}$	$V_{OUT} = V_{CC}$	25	35		mA
		$T_{min} < T < T_{max}$	10			
	$I_{source}$	$V_{OUT} = 0 \text{ V}$	30	37		
		$T_{min} < T < T_{max}$	15			
$I_{CC}$	Supply current (per channel)	No load, $V_{OUT} = V_{CC}/2$		295	345	$\mu\text{A}$
		$T_{min} < T < T_{max}$			420	
<b>AC performance</b>						
GBP	Gain bandwidth product	$R_L = 10 \text{ k}\Omega$ , $C_L = 100 \text{ pF}$	1.1	1.55		MHz
		$T_{min} < T < T_{max}$	0.8			
$\Phi_m$	Phase margin	$R_L = 10 \text{ k}\Omega$ , $C_L = 100 \text{ pF}$		45		degrees
$G_m$	Gain margin			18		dB
SR	Slew rate	$T = 25^\circ\text{C}$	0.35	0.58		$\text{V}/\mu\text{s}$
		$T_{min} < T < T_{max}$	0.20			
$E_N$	Equivalent input noise voltage	$f = 1 \text{ kHz}$		30		$\text{nV}/\sqrt{\text{Hz}}$
THD+N	Total harmonic distortion + noise	$f_{in} = 1 \text{ kHz}$ , Gain = 1, $R_L = 100 \text{ k}\Omega$ , $V_{icm} = (V_{CC} - 1 \text{ V}) / 2$ , BW = 22 kHz, $V_{OUT} = 1 \text{ Vpp}$			0.005	%
$C_S$	Channel separation	$f = 1 \text{ kHz}$		120		$\text{dB}$
$t_{rec}$	Overload recovery time			2		$\mu\text{s}$

**Table 8. Electrical characteristics**  $V_{CC+} = 36 \text{ V}$ ,  $V_{CC-} = 0 \text{ V}$ ,  $V_{icm} = V_{CC}/2$ ,  $T = 25^\circ\text{C}$ ,  $R_L = 10 \text{ k}\Omega$  connected to  $V_{CC}/2$  (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>DC performance</b>						
$V_{IO}$	Input offset voltage	$T = 25^\circ\text{C}$	-1		1	mV
		$T_{min} < T < T_{max}$	-1.6		1.6	
$ \Delta V_{IO}/\Delta T $	Input offset voltage drift	$T_{min} < T < T_{max}$		2		$\mu\text{V}/^\circ\text{C}$
$I_{IB}$	Input bias current	$T = 25^\circ\text{C}$		15	30	nA
		$T_{min} < T < T_{max}$			45	
$I_{IO}$	Input offset current	$T = 25^\circ\text{C}$		3	10	nA
		$T_{min} < T < T_{max}$			15	
$CMR$	Common mode rejection ratio: $20 \log (\Delta V_{icm}/\Delta V_{io})$	$V_{icm} = -0.1 \text{ to } V_{CC} - 1 \text{ V}$ , $V_{OUT} = V_{CC}/2$	105	135		dB
		$T_{min} < T < T_{max}$	100			
$SVR$	Supply voltage rejection ratio: $20 \log (\Delta V_{CC}/\Delta V_{io})$	$V_{CC} = 4.5 \text{ to } 36 \text{ V}$ , $V_{icm} = 0 \text{ V}$	100	124		dB
		$T_{min} < T < T_{max}$	95			
$A_{VD}$	Large signal voltage gain	$V_{OUT} = 0.5 \text{ V to } (V_{CC} - 0.5 \text{ V})$	105	120		dB
		$T_{min} < T < T_{max}$	100			
$V_{OH}$	High-level output voltage, $V_{OH} = V_{CC} - V_{OUT}$	$T = 25^\circ\text{C}$		110	140	mV
		$T_{min} < T < T_{max}$			180	
$V_{OL}$	Low-level output voltage	$T = 25^\circ\text{C}$		125	150	mV
		$T_{min} < T < T_{max}$			195	
$I_{OUT}$	$I_{sink}$	$V_{OUT} = V_{CC}$	35	45		mA
		$T_{min} < T < T_{max}$	15			
	$I_{source}$	$V_{OUT} = 0 \text{ V}$	35	45		
		$T_{min} < T < T_{max}$	25			
$I_{cc}$	Supply current (per channel)	No load, $V_{OUT} = V_{CC}/2$		310	375	$\mu\text{A}$
		$T_{min} < T < T_{max}$			420	
<b>AC performance</b>						
$GBP$	Gain bandwidth product	$R_L = 10 \text{ k}\Omega$ , $C_L = 100 \text{ pF}$	1.2	1.7		MHz
		$T_{min} < T < T_{max}$	0.95			
$\Phi_m$	Phase margin	$R_L = 10 \text{ k}\Omega$ , $C_L = 100 \text{ pF}$		45		degrees
$G_m$	Gain margin			18		dB
$SR$	Slew rate	$T = 25^\circ\text{C}$	0.35	0.60		$\text{V}/\mu\text{s}$
		$T_{min} < T < T_{max}$	0.25			
$E_N$	Equivalent input noise voltage	$f = 1 \text{ kHz}$		25		$\text{nV}/\sqrt{\text{Hz}}$
$THD+N$	Total harmonic distortion + noise	$f_{in} = 1 \text{ kHz}$ , Gain = 1, $R_L = 100 \text{ k}\Omega$ , $V_{icm} = (V_{CC} - 1 \text{ V}) / 2$ , BW = 22 kHz, $V_{OUT} = 1 \text{ Vpp}$		0.005		%
$C_S$	Channel separation	$f = 1 \text{ kHz}$		120		dB
$t_{rec}$	Overload recovery time			2		$\mu\text{s}$

## 4 Typical performance characteristics

Figure 4. Supply current vs. supply voltage

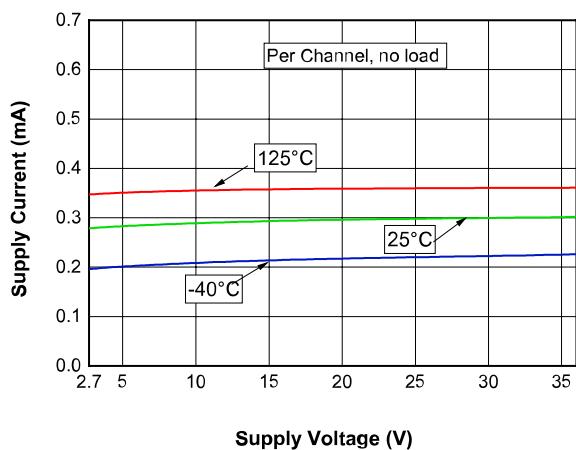


Figure 5. Input offset voltage distribution at  $V_{CC} = 2.7\text{ V}$

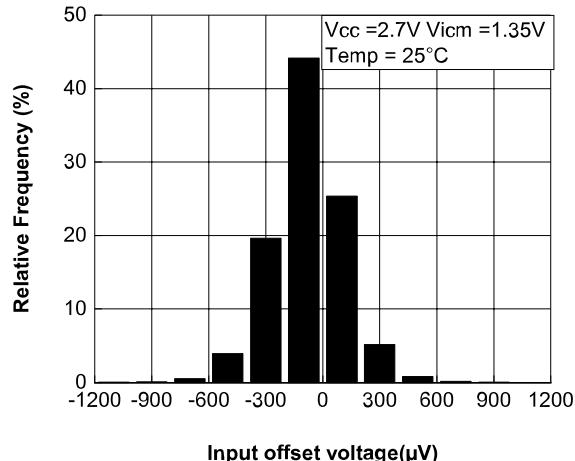


Figure 6. Input offset voltage distribution at  $V_{CC} = 12\text{ V}$

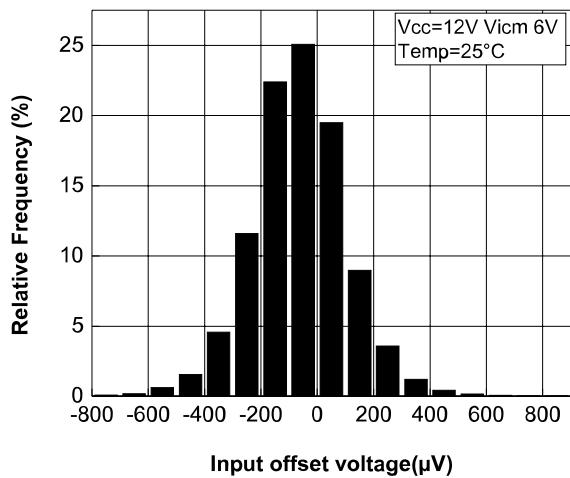
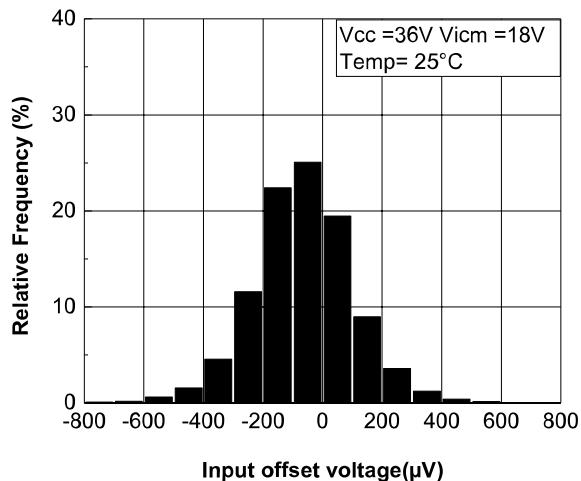
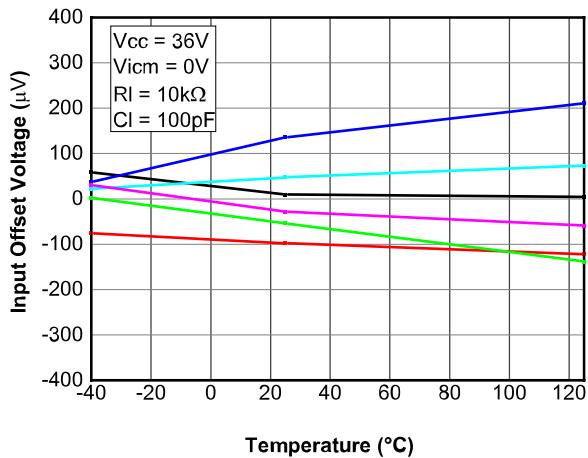


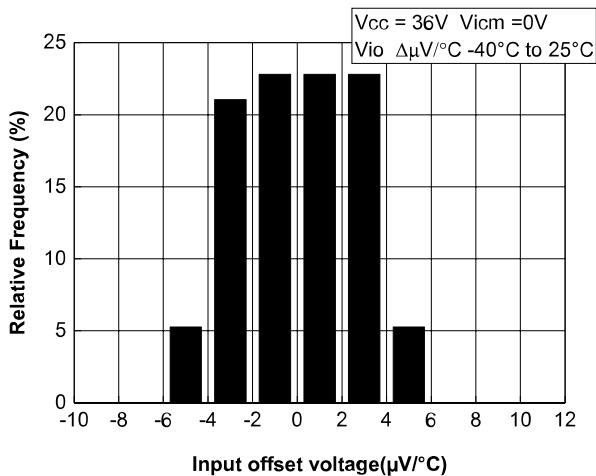
Figure 7. Input offset voltage distribution at  $V_{CC} = 36\text{ V}$



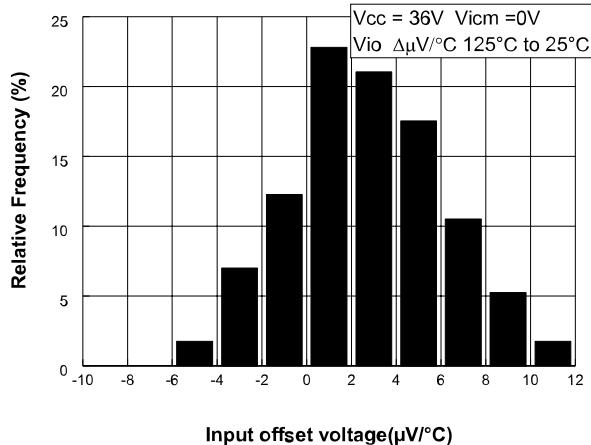
**Figure 8. Input offset voltage vs. temperature at  $V_{CC} = 36$  V**



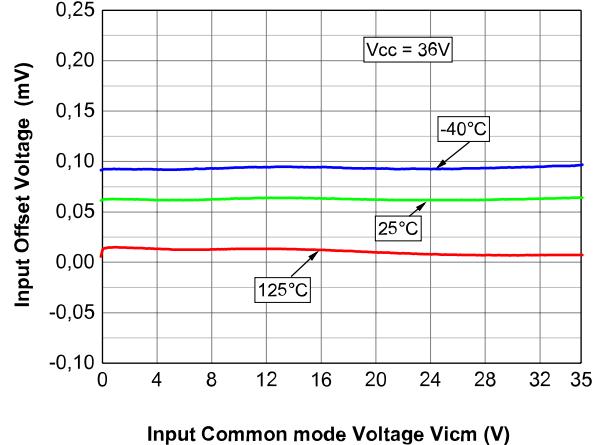
**Figure 9. Input offset voltage temperature variation distribution at  $V_{CC} = 36$  V**

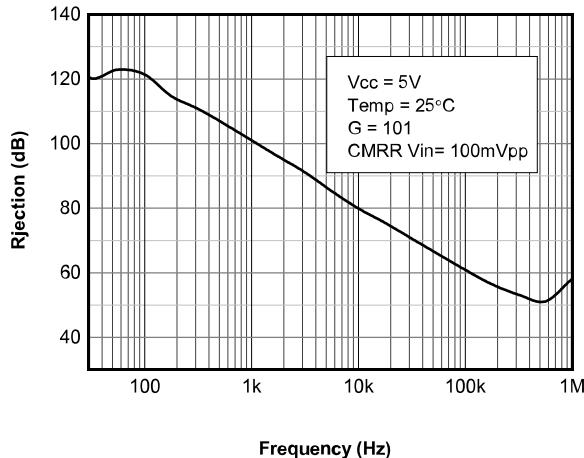
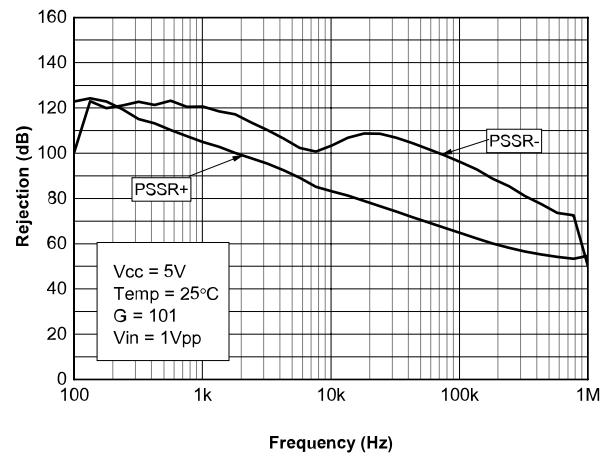
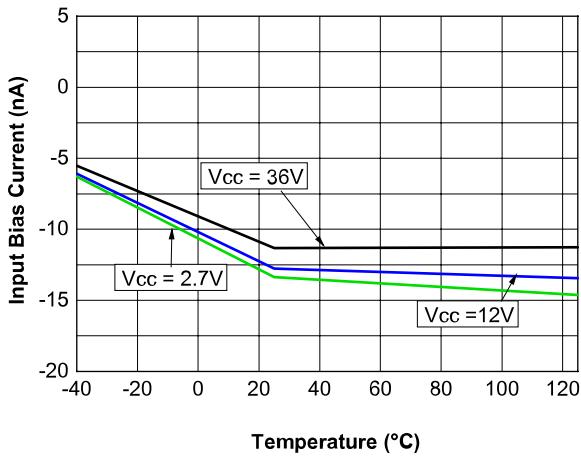
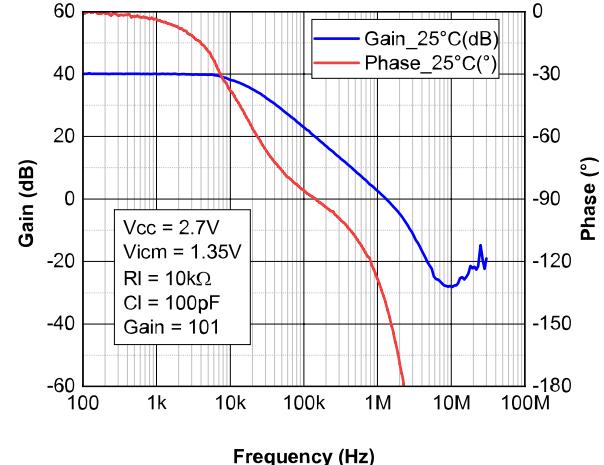


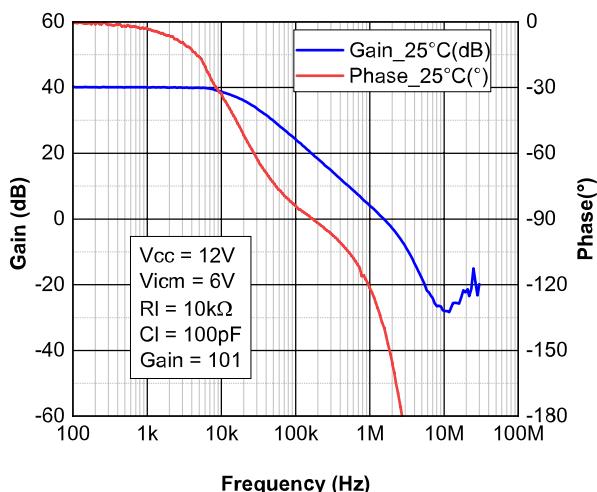
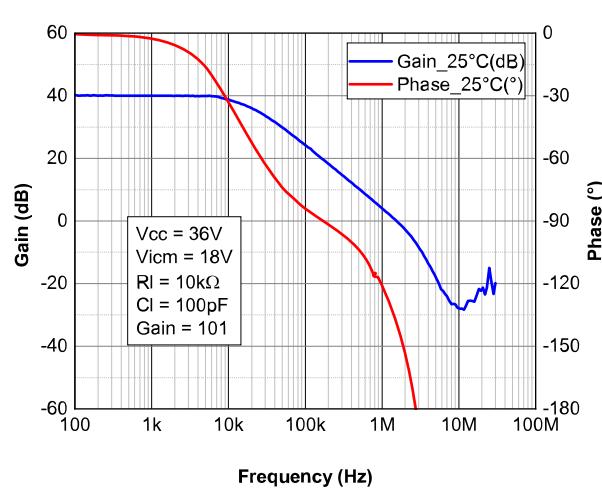
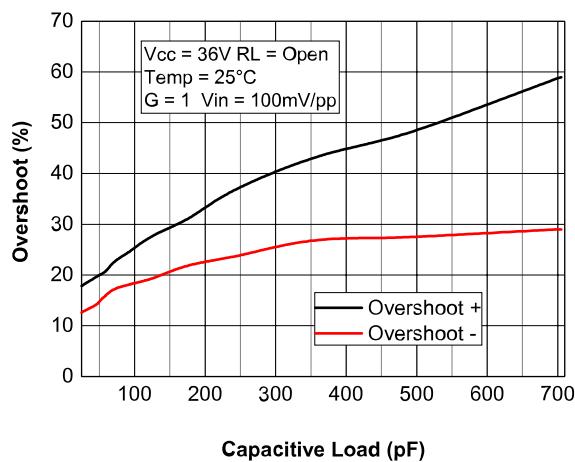
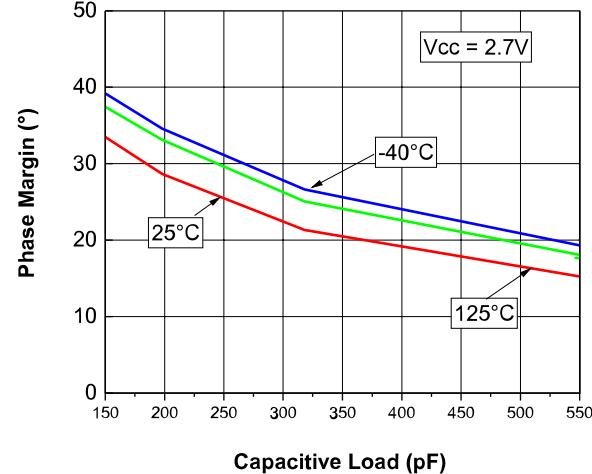
**Figure 10. Input offset voltage temperature variation distribution at  $V_{CC} = 36$  V**

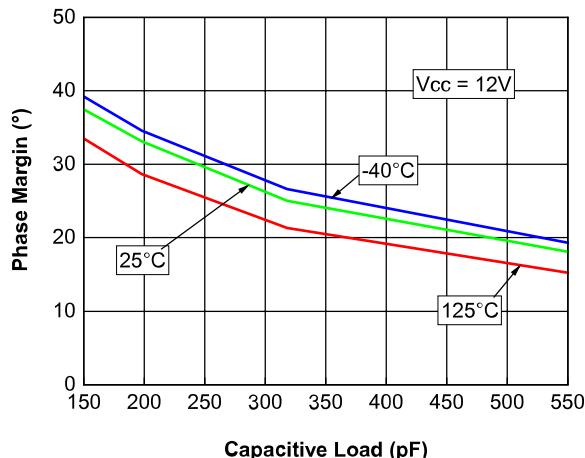
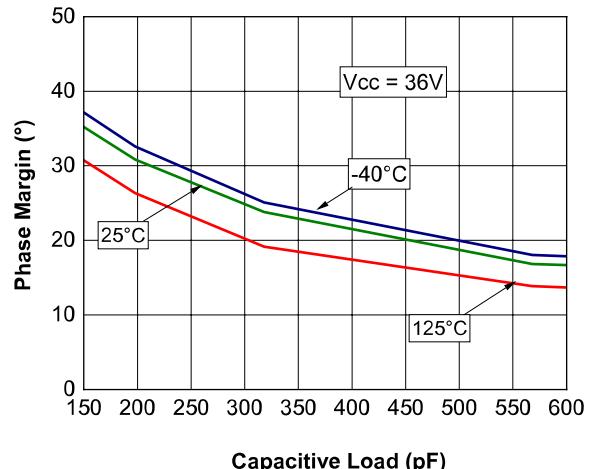
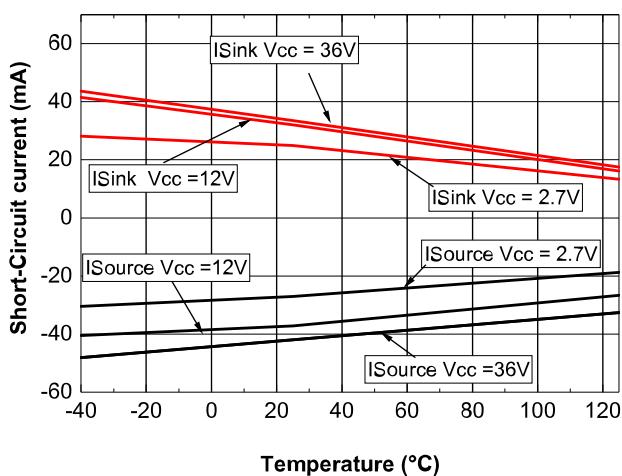
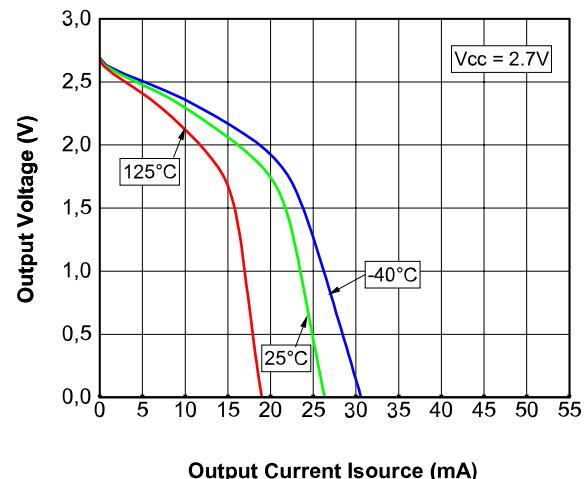


**Figure 11. Input offset voltage vs. common-mode voltage at  $V_{CC} = 36$  V**

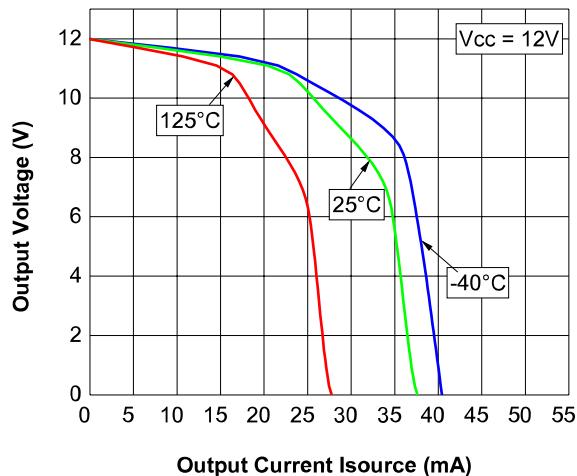


**Figure 12. Common-mode reject. ratio CMR at V<sub>CC</sub> = 5 V**

**Figure 13. Supply voltage rejection ratio SVR at V<sub>CC</sub> = 5 V**

**Figure 14. Input bias current vs. temperature**

**Figure 15. Bode diagram at V<sub>CC</sub> = 2.7 V**


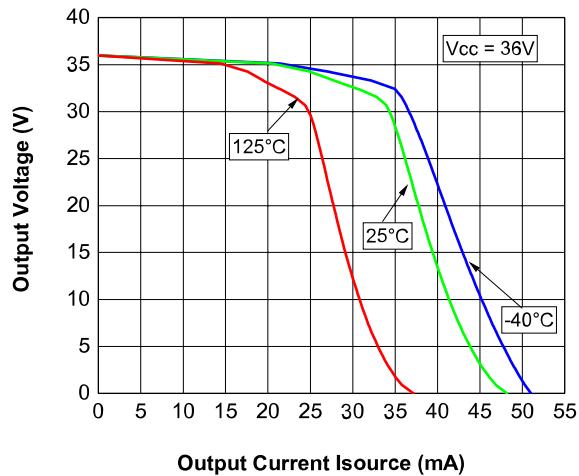
**Figure 16. Bode diagram at  $V_{CC} = 12\text{ V}$** 

**Figure 17. Bode diagram at  $V_{CC} = 36\text{ V}$** 

**Figure 18. Overshoot vs. capacitive load at  $V_{CC} = 36\text{ V}$** 

**Figure 19. Phase margin vs. capacitive load at  $V_{CC} = 2.7\text{ V}$** 


**Figure 20. Phase margin vs. capacitive load at  $V_{CC} = 12\text{ V}$** 

**Figure 21. Phase margin vs. capacitive load at  $V_{CC} = 36\text{ V}$** 

**Figure 22. Short-circuit current vs. temperature**

**Figure 23. Output source current vs. output voltage at  $V_{CC} = 2.7\text{ V}$** 


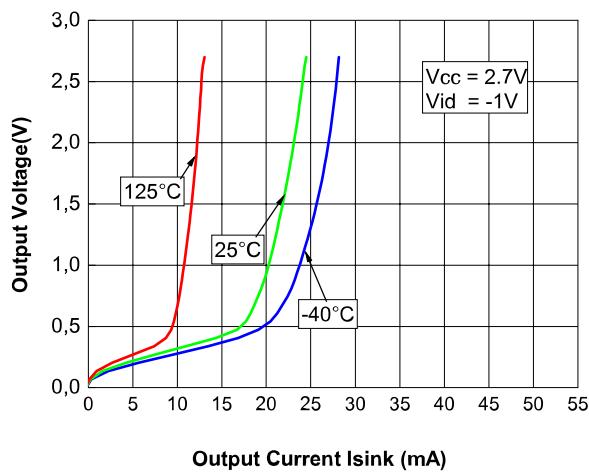
**Figure 24. Output source current vs. output voltage at  $V_{CC} = 12\text{ V}$**



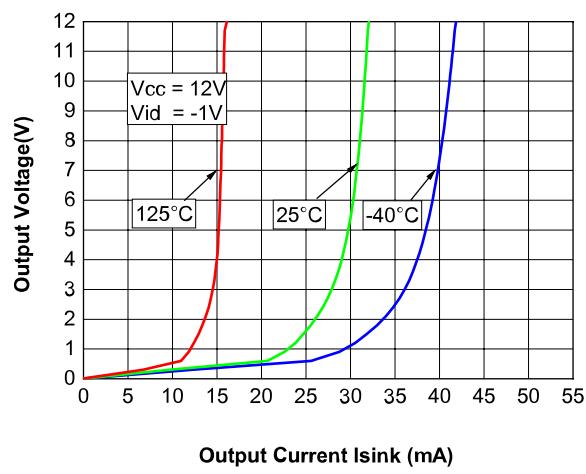
**Figure 25. Output source current vs. output voltage at  $V_{CC} = 36\text{ V}$**



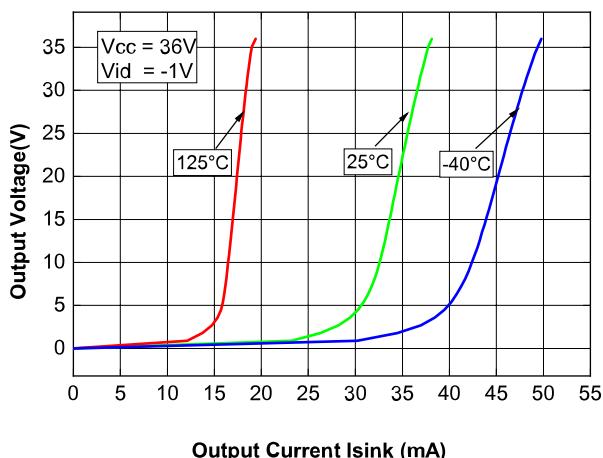
**Figure 26. Output sink current vs. output voltage at  $V_{CC} = 2.7\text{ V}$**



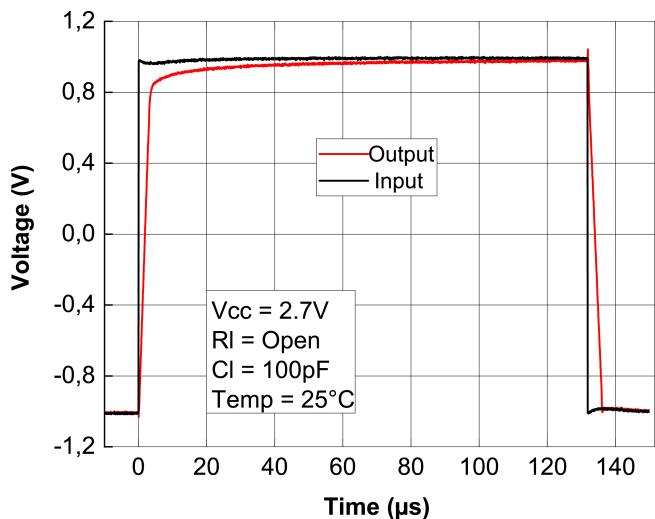
**Figure 27. Output sink current vs. output voltage at  $V_{CC} = 12\text{ V}$**



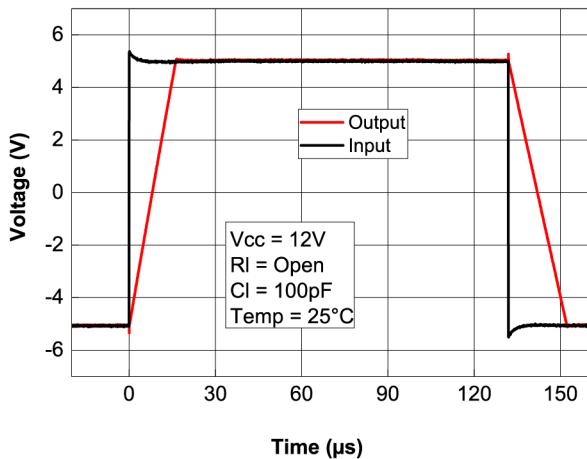
**Figure 28. Output sink current vs. output voltage at  $V_{CC} = 36 \text{ V}$**



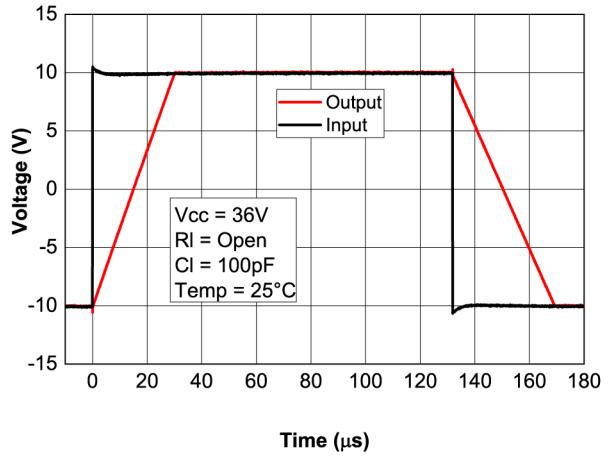
**Figure 29. Slew rate at  $V_{CC} = 2.7 \text{ V}$**

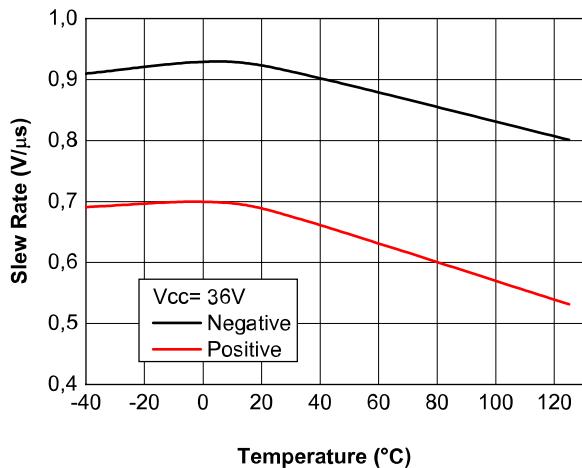
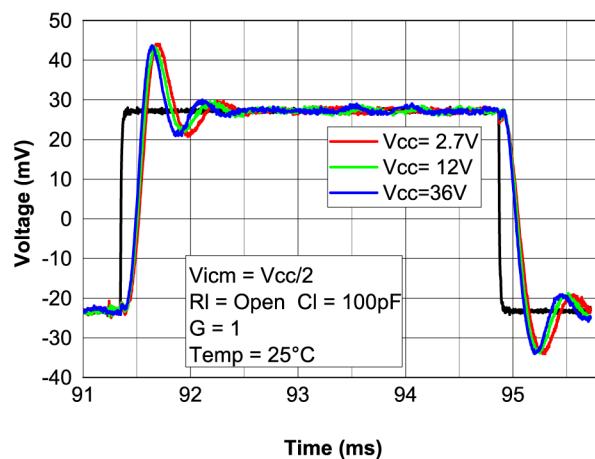
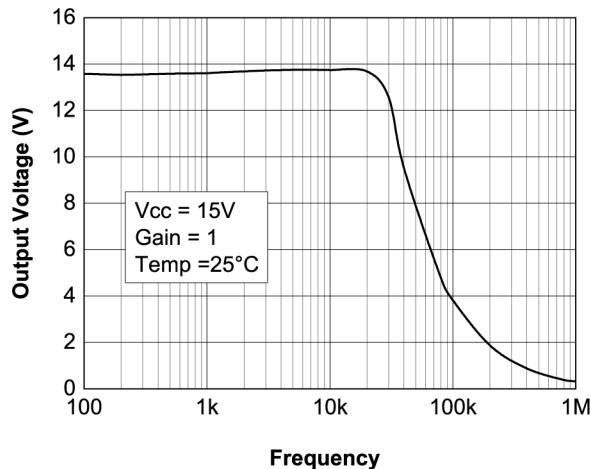
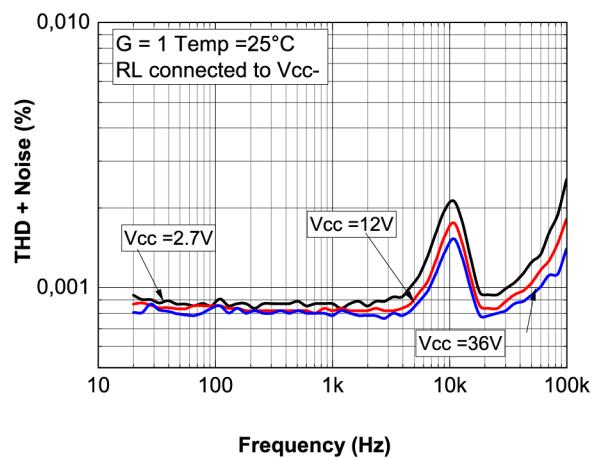


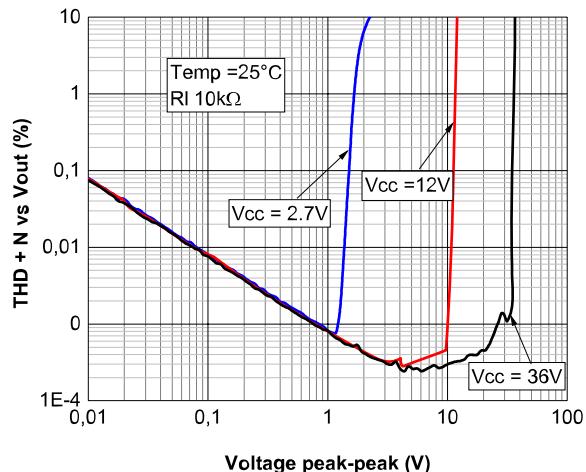
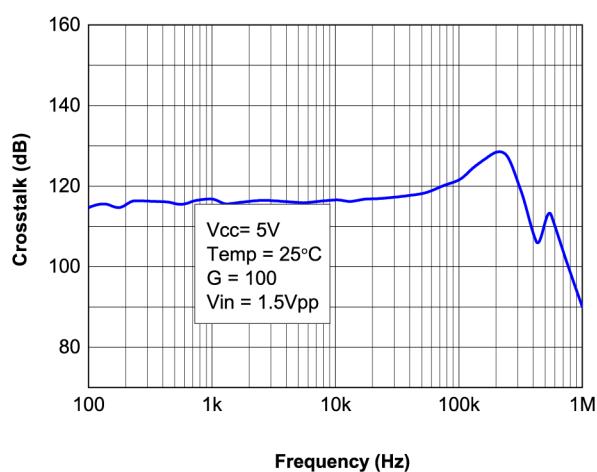
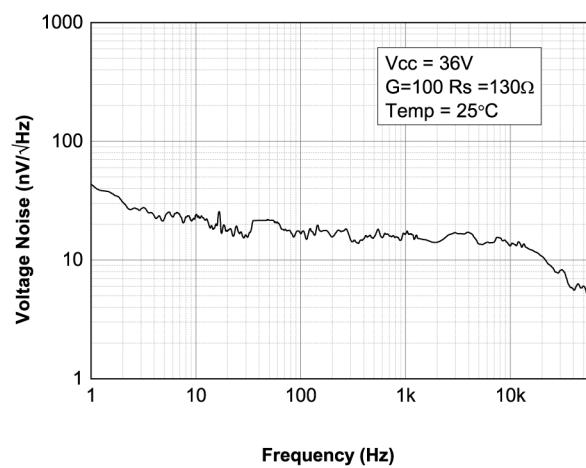
**Figure 30. Slew rate at  $V_{CC} = 12 \text{ V}$**



**Figure 31. Slew rate at  $V_{CC} = 36 \text{ V}$**



**Figure 32. Slew rate vs. temperature at  $V_{CC} = 36$  V**

**Figure 33. Small signal step response**

**Figure 34. Maximum output voltage vs. frequency**

**Figure 35. THD+Noise vs. frequency**


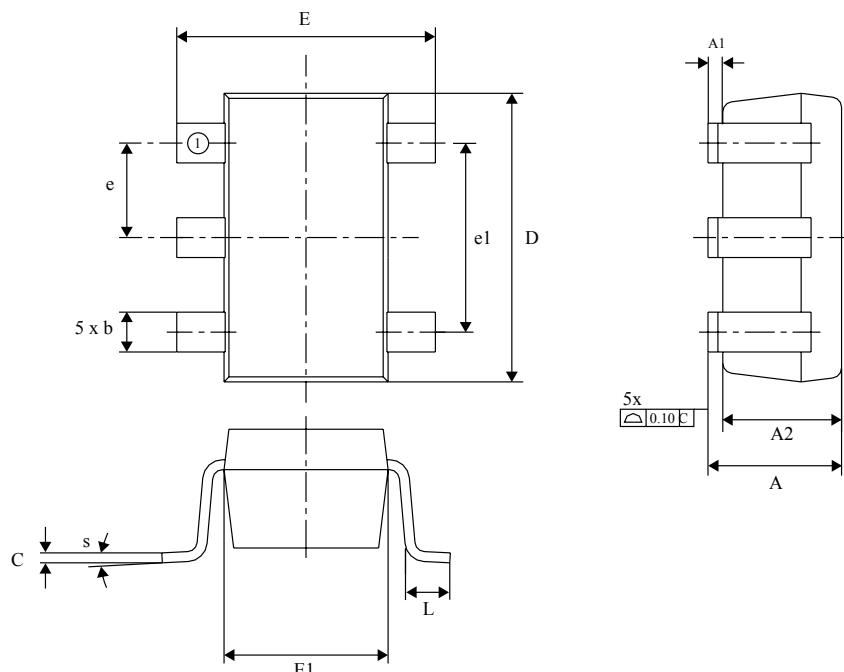
**Figure 36. THD+Noise vs. output voltage**

**Figure 37. Cross talk vs. frequency**

**Figure 38. Equivalent input noise voltage vs. frequency**


## 5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

## 5.1 SOT23-5 package information

Figure 39. SOT23-5 package outline



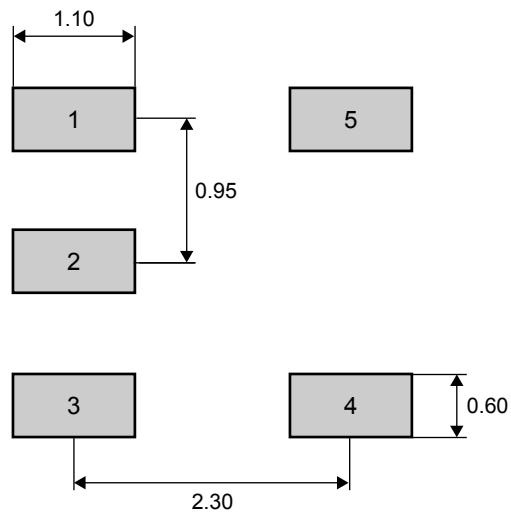
SOT23-5

Table 9. SOT23-5 mechanical data

Symbol	Millimeters			Inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.45			0.057
A1	0.00		0.15	0.000		0.006
A2	0.90	1.15	1.30	0.035	0.045	0.051
b	0.30		0.50	0.012		0.020
c	0.08		0.22	0.003		0.009
D		2.90			0.114	
E		2.80			0.110	
E1		1.60			0.063	
e		0.95			0.037	
e1		1.90			0.075	
L	0.30	0.45	0.60	0.012	0.018	0.024
$\theta$	0	4	8	0	4	8

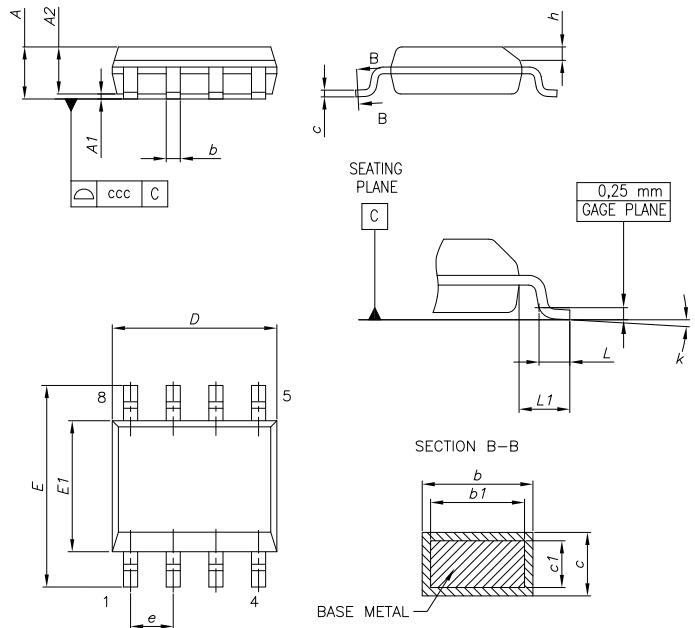
1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 40. SOT23-5 recommended footprint



## 5.2 SO8 package information

**Figure 41.** SO8 package outline

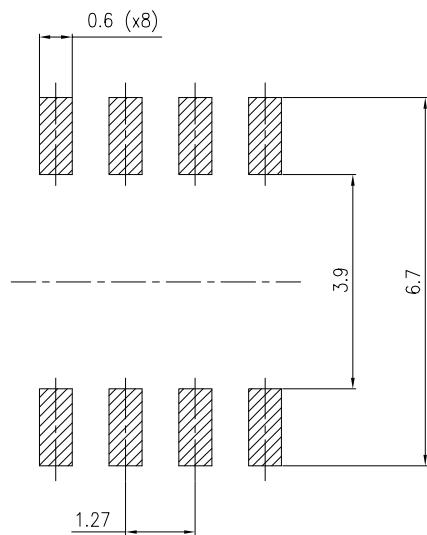


0016023\_So-807\_fig2\_Rev10

**Table 10.** SO8 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
c	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10

**Figure 42. SO8 recommended footprint**



## 5.3 MiniSO8 package information

Figure 43. MiniSO8 package outline

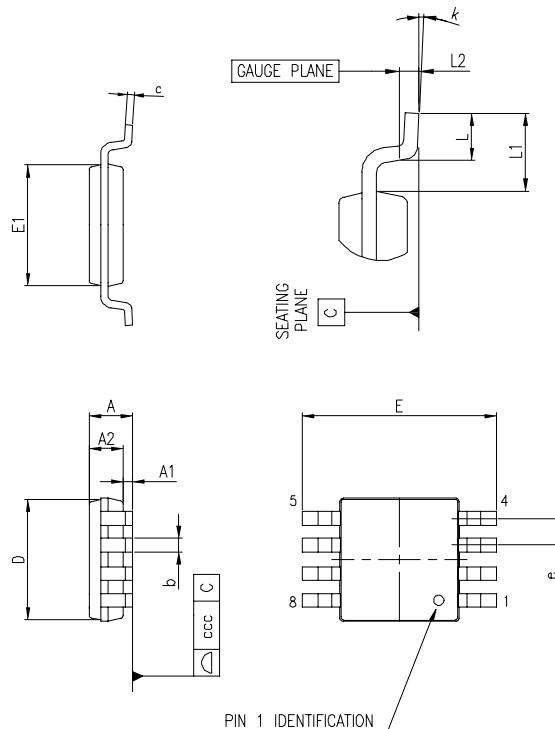
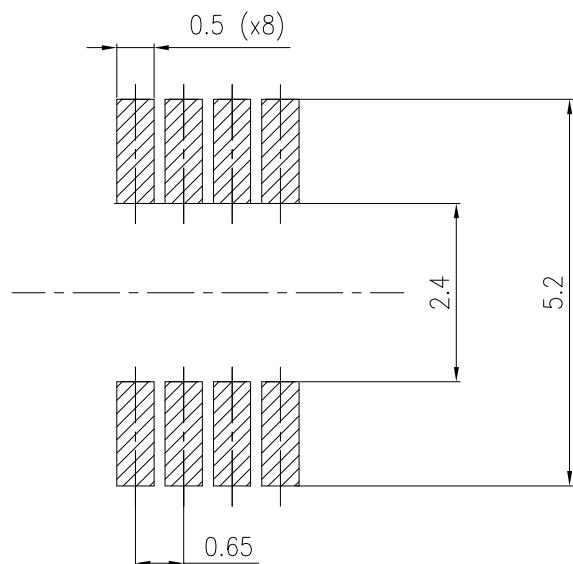


Table 11. MiniSO8 mechanical data

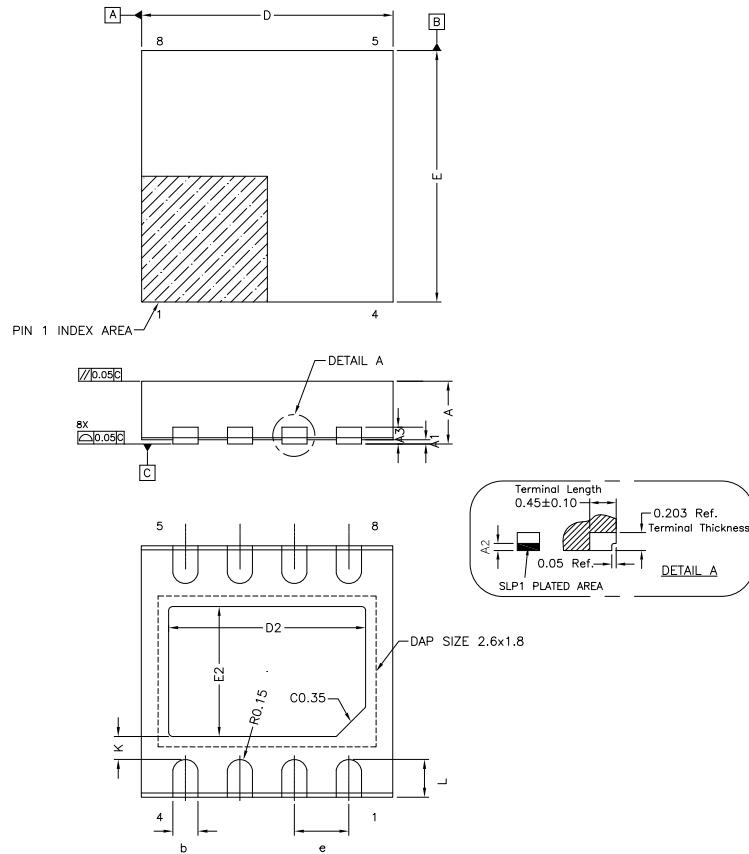
Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A				1.1		0.043
A1	0		0.15	0		0.006
A2	0.75	0.85	0.95	0.03	0.033	0.037
b	0.22		0.4	0.009		0.016
c	0.08		0.23	0.003		0.009
D	2.8	3	3.2	0.11	0.118	0.126
E	4.65	4.9	5.15	0.183	0.193	0.203
E1	2.8	3	3.1	0.11	0.118	0.122
e		0.65			0.026	
L	0.4	0.6	0.8	0.016	0.024	0.031
L1		0.95			0.037	
L2		0.25			0.01	
k	0°		8°	0°		8°
ccc			0.1			0.004

**Figure 44. MiniSO8 recommended footprint**



## 5.4 DFN8 3x3 wettable flanks package information (package code: A03Y)

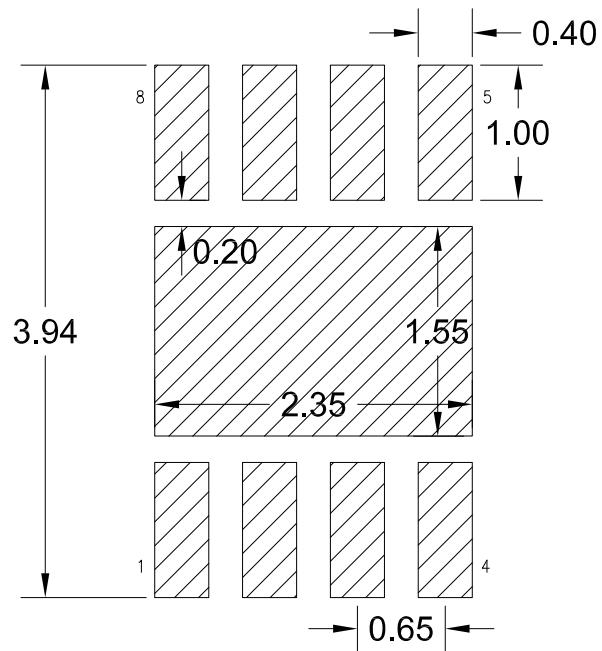
**Figure 45.** DFN8 3x3 package outline and mechanical data



**Table 12.** DFN8 3x3 mechanical data

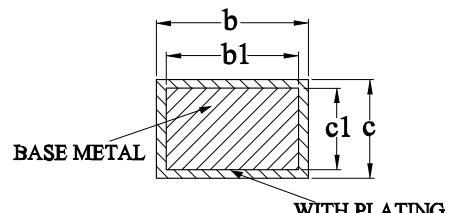
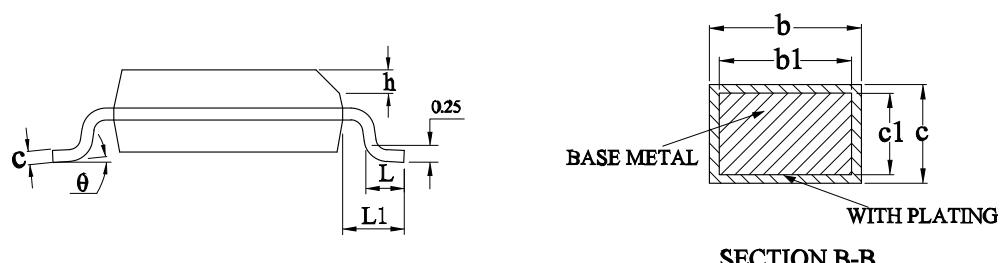
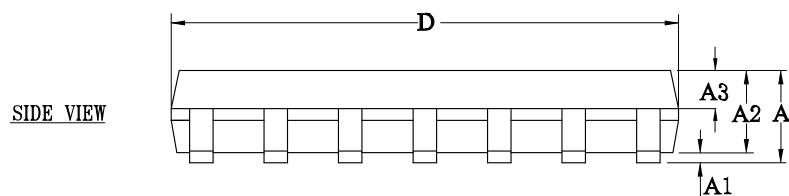
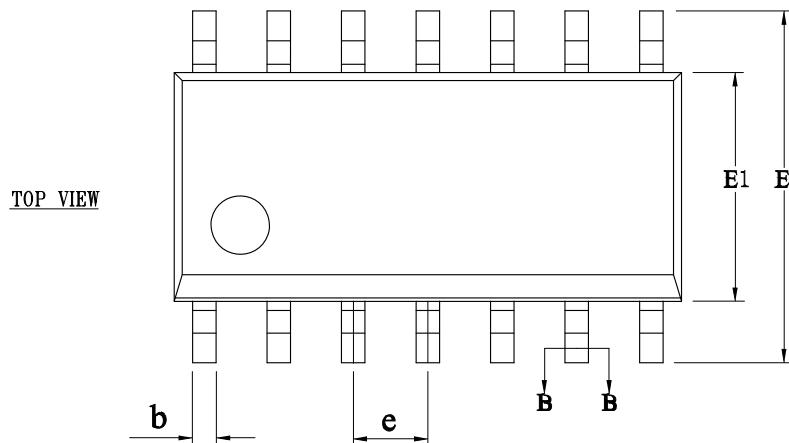
Symbol	mm		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.0		0.05
A2	0.10		
A3		0.20 Ref.	
b	0.25	0.30	0.35
D	2.95	3.00	3.05
D2	2.25	2.35	2.45
e		0.65 BSC	
E	2.95	3.00	3.05
E2	1.45	1.55	1.65
L	0.35	0.45	0.55
K		0.275 Ref.	

Figure 46. DFN8 3x3 footprint data



## 5.5 SO14 package information

Figure 47. SO14 package outline

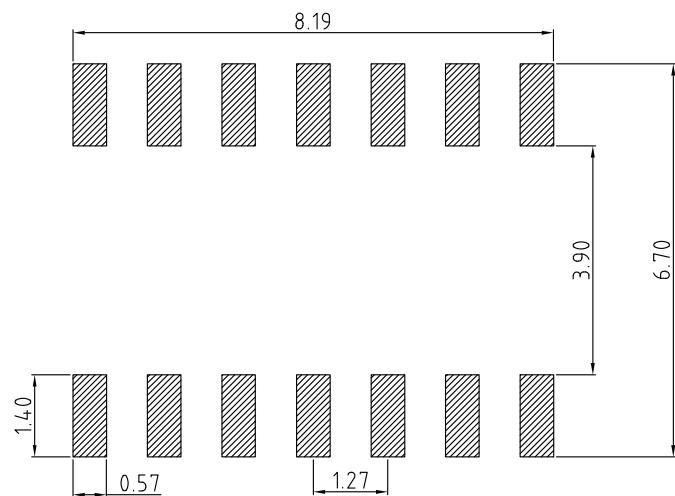


SECTION B-B

Table 13. SO14 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.225
A2	1.30	1.40	1.50
A3	0.60	0.65	0.70
b	0.39		0.47
b1	0.38	0.41	0.44
c	0.20		0.24
c1	0.19	0.20	0.21
D	8.55	8.65	8.75
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27 BSC	
h	0.25		0.50
L	0.50		0.80
L1		1.05 REF	
	0		8°

Figure 48. SO14 recommended footprint



## 5.6 TSSOP14 package information

Figure 49. TSSOP14 package outline

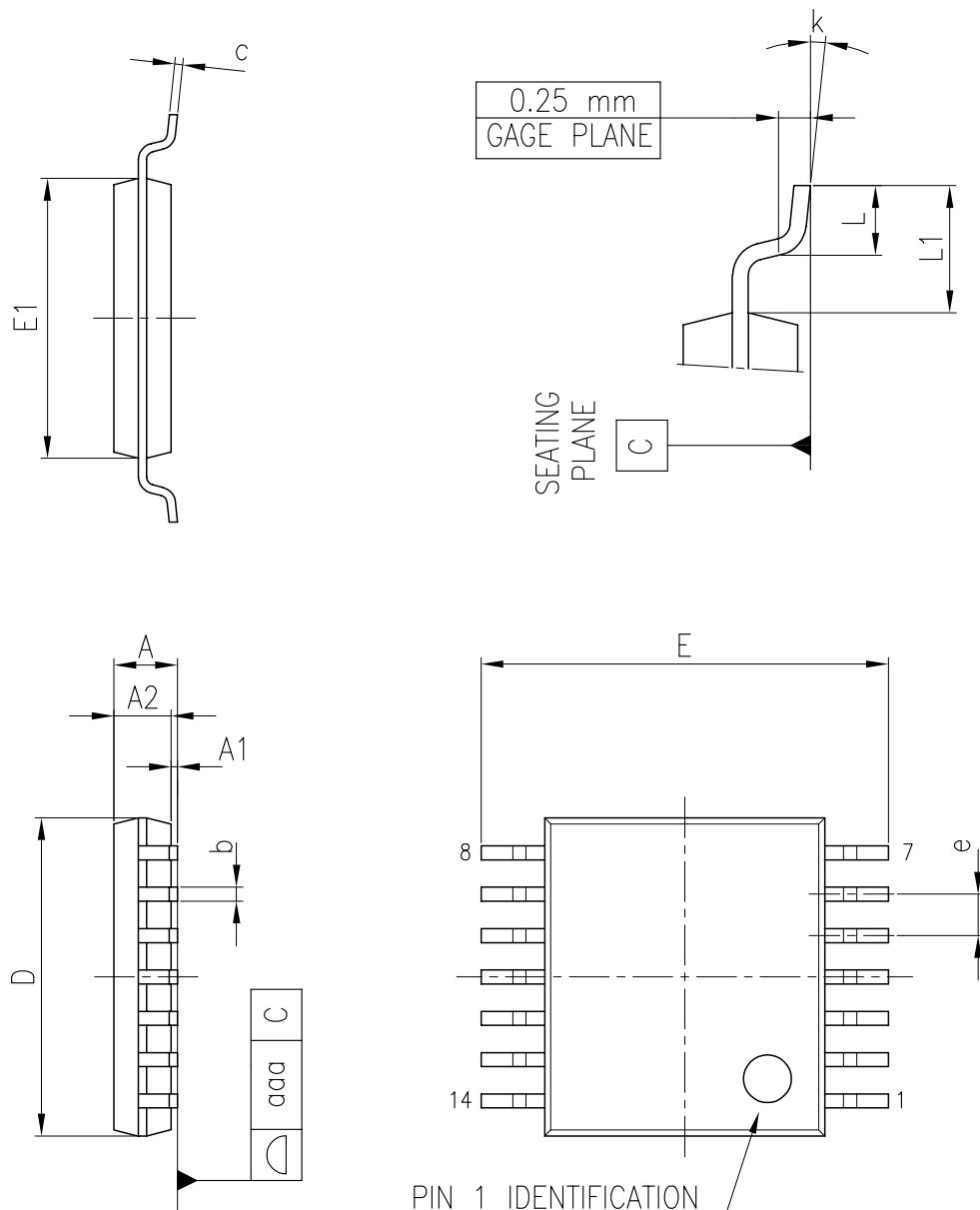


Table 14. TSSOP14 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.20
A1	0.05		0.15
A2	0.80	1.00	1.05
b	0.19		0.30
c	0.09		0.20
D	4.90	5.00	5.10
E	6.20	6.40	6.60
E1	4.30	4.40	4.50
e		0.65	
L	0.45	0.60	0.75
L1		1.00	
k	0°		8°
aaa			0.10

## 6 Ordering information

Table 15. Order code

Order code	Package	Packaging	Marking
TSB621ILT	SOT23-5		K2K
TSB621IYLT <sup>(1)</sup>			K2L
TSB622IDT	SO8		TSB622I
TSB622IYDT <sup>(1)</sup>			TSB622IY
TSB622IST	MiniSO8		K2K
TSB622IYST <sup>(1)</sup>			K2L
TSB622IQ3T	DFN8 3x3 WF	Tape & Reel	K2K
TSB622IYQ3T <sup>(1)</sup>			K2L
TSB624IDT	SO14		TSB624I
TSB624IYDT <sup>(1)</sup>			TSB624IY
TSB624IPT	TSSOP14		TSB624I
TSB624IYPT <sup>(1)</sup>			TSB624IY

1. Qualified and characterized according to AEC Q100 and Q003 or equivalent, advanced screening according to AEC Q001 & Q002 or equivalent.

## Revision history

**Table 16. Document revision history**

Date	Revision	Changes
03-Nov-2021	1	Initial release.
15-Feb-2022	2	Updated Figure 2.
01-Dec-2022	3	Added new TSSOP14, SO14 and SOT23-5 packages in <a href="#">Section 5 Package information</a> . Updated <a href="#">Section 1 Pin connections</a> , <a href="#">Table 4. Absolute maximum ratings</a> , phase margin typical value in <a href="#">Table 6</a> , <a href="#">Table 7</a> , <a href="#">Table 8</a> and <a href="#">Section 6 Ordering information</a> .

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